



Product/Process Change Notification Form

PCN Number:	PCN-2014-0487
Date of Notification:	7/16/2014
Apex P/N(s):	SA09, SA12, SA12-13
Date PCN Effective:	10/1/2014
Reason for Change:	<input type="checkbox"/> Design /New Rev. <input type="checkbox"/> Assembly Site <input checked="" type="checkbox"/> Assembly Process <input type="checkbox"/> Other (specify) Internal semiconductor chip thickness variation
Description of Change:	The temperature sense devices are now mounted directly to the top surface of the MOSFET output devices.
Apex P/N Change:	<input type="checkbox"/> Yes, New Part Number: <input checked="" type="checkbox"/> No
Lot Effective Date:	10/1/14
Quality & Reliability impact:	Qualification Data: <input type="checkbox"/> Required <input checked="" type="checkbox"/> Not Required
Datasheet Change Required?	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain: